

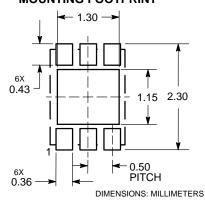
6x L

E2 фπг CAB 0.10 е Ф 0.05 C NOTE 3 **BOTTOM VIEW**

MOUNTING FOOTPRINT

D2

DETAIL A



*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DFN6 1.6x2.0, 0.5P

DATE 11 NOV 2008

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND
- 0.20 mm FROM THE TERMINAL TIP.
 COPLANARITY APPLIES TO THE EXPOSED
 PAD AS WELL AS THE TERMINALS.

	MILLIMETERS			
DIM	MIN	MAX		
Α	0.80	1.00		
A1	0.00	0.05		
A3	0.20 REF			
b	0.20	0.40		
D	1.60 BSC			
D2	1.10	1.30		
Е	2.00 BSC			
E2	0.95	1.15		
е	0.50 BSC			
K	0.20			
L	0.15	0.35		
L1		0.10		

GENERIC MARKING DIAGRAM*



XX = Specific Device Code

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part

Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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